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TITLE: FC CBGA, WITH CAP ZONES 25 X 25 X 2.8 PKG, 1.27MM PITCH, 360 I/O	DOCUMENT NO: 98ARS10521D	REV: A
	STANDARD: JEDEC M0-156 VAR BBJ	
	SOT1603-4	04 JAN 2016



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.

2. ALL DIMENSIONS IN MILLIMETERS.

3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. CAPACITORS MAY NOT BE PRESENT ON ALL DEVICES.

6. CAUTION MUST BE TAKEN NOT TO SHORT EXPOSED METAL CAPACITOR PADS ON PACKAGE TOP.

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